

**ABLESTIK ABP 8060T**

April 2012

**PRODUCT DESCRIPTION**

ABLESTIK ABP 8060T provides the following product characteristics:

|                                    |                                                                                                                                                                                                        |
|------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>Technology</b>                  | BMI Hybrid                                                                                                                                                                                             |
| <b>Appearance</b>                  | Silver paste                                                                                                                                                                                           |
| <b>Product Benefits</b>            | <ul style="list-style-type: none"><li>• Hydrophobic</li><li>• Electrically conductive</li><li>• Thermally conductive</li><li>• Stable at high temperatures</li><li>• High die shear strength</li></ul> |
| <b>Cure</b>                        | Heat cure                                                                                                                                                                                              |
| <b>Application</b>                 | Die attach                                                                                                                                                                                             |
| <b>Typical Package Application</b> | MOSFET                                                                                                                                                                                                 |

ABLESTIK ABP 8060T is formulated to provide high heat transfer generated from power devices. This material can also be used as a soft solder alternate for applications requiring high thermal and electrical conductivity.

**TYPICAL PROPERTIES OF UNCURED MATERIAL**

|                                                |        |
|------------------------------------------------|--------|
| Thixotropic Index (0.5/5 rpm)                  | 6.0    |
| Viscosity, Brookfield CP51, 25 °C, mPa·s (cP): |        |
| Speed 5 rpm                                    | 12,000 |
| Filler Content, %                              | 85     |
| Work Life @ 25°C, hours                        | 24     |
| Flash Point - See MSDS                         |        |

**TYPICAL CURING PERFORMANCE****Cure Schedule**

45 minutes ramp from 25°C to 200°C + 60 minutes @ 200°C in N<sub>2</sub> or air oven

**Alternative Cure Schedule**

30 minutes ramp from 25°C to 175°C + 60 minutes @ 175°C in N<sub>2</sub> or air oven

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

**TYPICAL PROPERTIES OF CURED MATERIAL****Physical Properties**

|                                          |                                            |
|------------------------------------------|--------------------------------------------|
| Coefficient of Thermal Expansion, TMA:   |                                            |
| Alpha 1, ppm                             | 55                                         |
| Alpha 2, ppm                             | 120                                        |
| Tensile Modulus, DMTA:                   |                                            |
| @ 25°C                                   | N/mm <sup>2</sup> 6,230<br>(psi) (903,005) |
| @ 250°C                                  | N/mm <sup>2</sup> 1,730<br>(psi) (251,495) |
| Extractable Ionic Content, @ 100°C, ppm: |                                            |
| Chloride (Cl <sup>-</sup> )              | <10                                        |
| Sodium (Na <sup>+</sup> )                | <10                                        |
| Potassium (K <sup>+</sup> )              | <10                                        |
| Thermal Conductivity, W/(m·K)            | 20                                         |

**Electrical Properties**

|                            |                      |
|----------------------------|----------------------|
| Volume Resistivity, ohm-cm | 2.5×10 <sup>-5</sup> |
|----------------------------|----------------------|

**TYPICAL PERFORMANCE OF CURED MATERIAL****Miscellaneous****Die Shear Strength:**

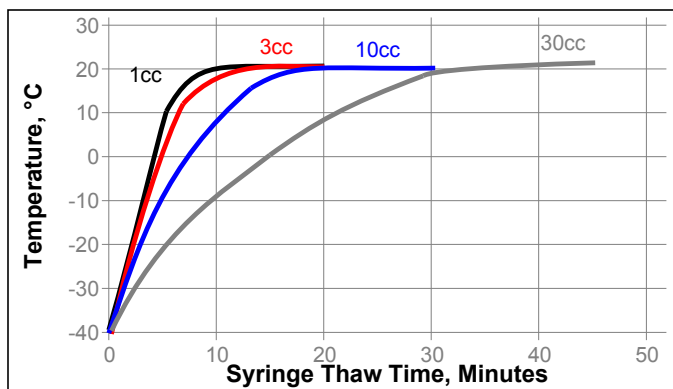
|                                                    |      |
|----------------------------------------------------|------|
| 1.27 X 1.27 mm (50 x 50 mil) Bare Si Die, Kg:      |      |
| @ 25°C                                             | >2.3 |
| @ 260°C                                            | >1.3 |
| 1.02 X 1.02 mm (40 x 40 mil) Ag backmetal die, Kg: |      |
| @ 25°C                                             | >2.0 |
| @ 260°C                                            | >1.3 |

**GENERAL INFORMATION**

**For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).**

**THAWING:**

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. Refer to the Syringe Thaw time chart for the thaw time recommendation.
4. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
5. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.



#### DIRECTIONS FOR USE

1. Thawed adhesive should immediately be placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Silver-resin separation may occur if the adhesive is left out at 25°C beyond the recommended work life.
4. Adhesive must be completely used within the product's recommended work life.
5. Alternate dispense amounts may be used depending on the application requirements..
6. Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

#### Optimal Storage : -40 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$   
 $\text{kV/mm} \times 25.4 = \text{V/mil}$   
 $\text{mm} / 25.4 = \text{inches}$   
 $\text{N} \times 0.225 = \text{lb}$   
 $\text{N/mm} \times 5.71 = \text{lb/in}$   
 $\text{N/mm}^2 \times 145 = \text{psi}$   
 $\text{MPa} \times 145 = \text{psi}$   
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$   
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$   
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$   
 $\text{mPa}\cdot\text{s} = \text{cP}$

#### Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation and its affiliates ("Henkel") specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel products. Henkel specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Americas  
+1.888.943.6535

Europe  
+44.1442.278.000

Asia  
+86.21.3898.4800

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